

Description

EW 6615 is a two-part epoxy adhesive. It contains a high load of fillers rendering it low shrinkage. It is ideal for component potting and bonding.

Features

- Recommended substrates: PA, stainless steel, PCB
- Low CTE
- Thixotropic
- Excellent resistance against moisture, weathering thermal shocks and mechanical stress

Uncured Properties

Chemical Type	Epoxy
Appearance	
Part A	Black
Part B	Light Yellow
Viscosity @ 25°C [mPa·s]	
Brookfield DV2T, spindle 14# @ 20rpm	
Part A	16,000
Part B	7,500
After mixed	18,000
Mix Ratio A:B	
By Weight	2:1
By Volume	2:1
Specific Gravity [g/cm³]	
Part A	1.4
Part B	1.4
Shelf Life @ 10-28°C [months]	12

Curing Condition

Setting Time [mins]	45
@ 25°C (30g adhesive mixed)	
Full Strength	
@ 25°C [days]	4
@ 80°C [hrs]	1

Cured Properties

Hardness [Shore D]	65
ASTM D2240	
Lap Shear Strength [MPa]	
Al / Al	>16
ASTM D1002	
Coefficient of Thermal Expansion (CTE) [ppm/K]	
Above Tg	155
ASTM D696	
Elongation at break [%]	8
ASTM D638	
Surface Resistivity [ohm·cm]	>1.0x10 ¹⁴
ASTM D257	
Volume Resistivity [ohm·cm]	>1.0x10 ¹⁴
ASTM D257	
Dielectric Strength [V/mil]	350
ASTM D149	

Directions for Use

1. Surface Treatment

Surfaces to be bonded should be free of dust, oil, grease or any other contaminants in order to achieve a reproducible bond. For slightly contaminated surfaces, it is sufficient to wipe with isopropanol or ethanol. Substrates with a low surface energy (e.g. polyethylene, polypropylene, Teflon) need to be pre-treated physically (e.g. atmospheric plasma or corona) in order to achieve sufficient adhesion.

2. Application

Products are supplied ready for use. Depending on package type, they can be dosed manually, semi-automatically or fully-automatically with a dosage apparatus. With automatic dispensing using a cartridge, the adhesive is conveyed via pressure and a piston rod to a dispense valve. With bottles, the adhesive is conveyed using a pump.

After application, it is recommended that the two substrates be adjoined immediately as it is possible the curing process will begin with select products under ambient conditions.

3. Suggested working temperature range is -40 to 150°C.

Storage

Maximum shelf life may be obtained when product is stored in a cool, dry location at a temperature between **10°C to 28°C**.

TO PREVENT CONTAMINATION OF UNUSED PRODUCT, DO NOT RETURN ANY PRODUCT TO ITS ORIGINAL CONTAINER.

Materials Handling

Refer to the Material Safety Data Sheet (MSDS) for this product.

Disclaimer

The information provided here including the recommendations for use and application of the product is based on internal laboratory test conditions and should only be used as a reference. CollTech does not assume responsibility for the test or performance results obtained by the user. It is the responsibility of the user to perform their own evaluations to confirm whether this product is suitable for their application.